TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130218001
DM6 U*BGA Cu Wire Bond conversion
Change Notification / Sample Request

Date: 3/25/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 90 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130218001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320VC5503GHH	null
TMS320VC5506GHH	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130218001	**PCN Date:**	03/25/2013

Title:	DM6 U*BGA Cu Wire Bond conversion for 90nm and 120nm products

Customer Contact:	PCN_ww_admin_team@list.ti.com	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	06/25/2013	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☒	Assembly Materials

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. See table below:

Material Set	Current Assembly Au wire	Cu Bond wire option
Wire diam (Mils)	0.96	0.80

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

None.

Product Affected:

D35004AZGW160	TMS320DM100ZJJR	TMS320VC5506GHH	TMS320VC5510AZGW1
D35004AZGWA200	TMS320DM270ZHK-K	TMS320VC5506ZHHR	TMS320VC5510AZGWD2
D751685AM3ZZAR	TMS320DM299DZJJ	TMS320VC5507ZHH	TNETV2510ENGGWR
D751685AZZAR	TMS320DM299ZJJR	TMS320VC5507ZHHR	TNETV2510GGWR
D761924ZGUR	TMS320SP109AZHH	TMS320VC5509AGHHR	
OMAP5910JGZG2	TMS320VC5503GHH	TMS320VC5510AGPHA2	

Qualification Data: Approved 11/29/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: D6567GN0ZWKR (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4206745
# Pins-Designator, Family:	385-ZWK, BGA	Mount Compound:	4073505
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**Biased Temp Humidity	85C/85%RH (600hrs)	78/0	-	-
**Unbiased HAST	110C/85%RH (264hrs)	78/0	78/0	78/0
**High Temp. Storage Bake	150C (600 hrs)	78/0	78/0	78/0
**T/C -65C/150C	-55C/+125C (1000 Cyc)	78/0	78/0	78/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes	**- Preconditioning sequence: Level 3-260C.			

Qual Vehicle 2: F761536ZZD (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4203565
# Pins-Designator, Family:	179-ZZD, BGA	Mount Compound:	4111062
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
** Biased HAST	110C/85%RH, 264 hrs	70/0	70/0	70/0
** Unbiased HAST	130C/85%RH (192hrs)	98/0	99/0	99/0
** Unbiased HAST	110C/85%RH (192hrs)	97/0	97/0	96/0
**High Temp. Storage Bake	150C (1008 hrs)	96/0	97/0	97/0
**T/C -65C/150C	-55C/+125C (1000 Cyc)	101/0	103/0	101/0
Notes	**- Preconditioning sequence: Level 3-260C.			

Qual Vehicle 3: TSB43DA42AGHC (MSL 3-260C)

Package Construction Details

Assembly Site:	PHI (TIPI)	Mold Compound:	4203565
# Pins-Designator, Family:	196-GHC, BGA	Mount Compound:	4111062
Solder Ball composition	SnAgCu	Bond Wire:	0.80Mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	150C (1008 hrs)	90/0	90/0	90/0
**Biased Temp and Humidity	85C/85%RH (600hrs)	77/0	77/0	77/0
** Unbiased HAST	130C/85%RH (192hrs)	90/0	90/0	90/0
**T/C -65C/150C	-55C/+125C (1000 Cyc)	110/0	110/0	110/0
Notes	**- Preconditioning sequence: Level 3-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com